

On Membrane Attenuators for 60 GHz Loopback Transceiver Testing



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Agenda

- Background
- Problem Discussion
- Analysis
- Solution
- Design
- Validation
- Conclusions



Problem Statement

STMicroelectronics has observed variable attenuation across sites in their Receiver Signal Strength Indicator (RSSI) signal causing test failures and delays in their production test.







Technology Background SFORMFACTOR®



STMicroelectronics ST60A3

60 GHz V-Band transceiver for contactless connectivity up to 480 Mbps















Video Walls





Camera













Small footprint with integrated antenna



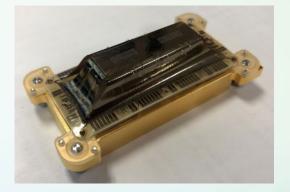
Ultra low power

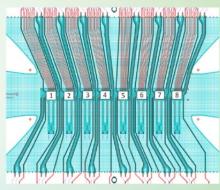


-20°C to 85°C

FormFactor Pyramid Probe P800s

Most widely qualified wafer test solution for production test





- Frequency range to 67 GHz with better than -10 dB Return Loss (RL) to maximize test accuracy out to specified frequency
- Multi-site 5G antenna and RFFE die testing
- Probe geometries engineered for low contact resistance on pads and solder



Test Strategy

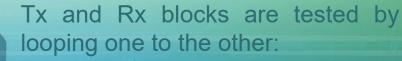
Measurement Challenge: To test the ST60A3 requires expensive equipment. This results in high cost of test. To reduce cost, a test technique called loopback testing was employed.

Implantation Requirements:

 Loopback path needs a high level of attenuation to ensure the transmitter (Tx) doesn't saturate the receiver (Rx).

- Wafer on bump testing
- Use x8 parallelism







Loopback Testing

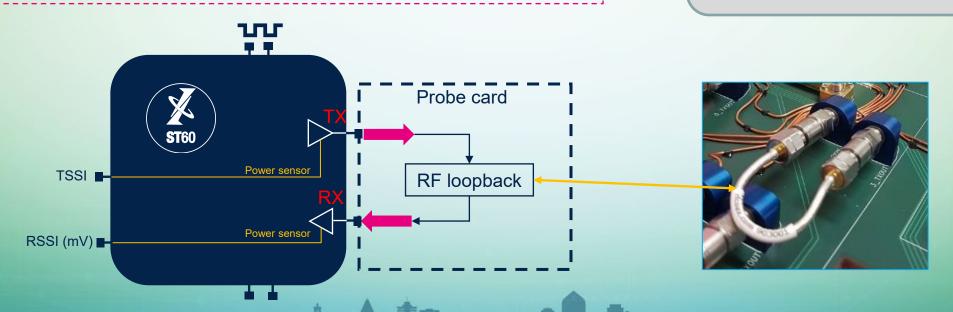
Output power at TX

 P_{OUT} calibrated at fixed level and verified through TSSI (Transmitter signal strength indicator)

Input power at RX

P_{IN} at RX is evaluated from RSSI (Receiver signal strength indicator) measurement on ATE (in mV)

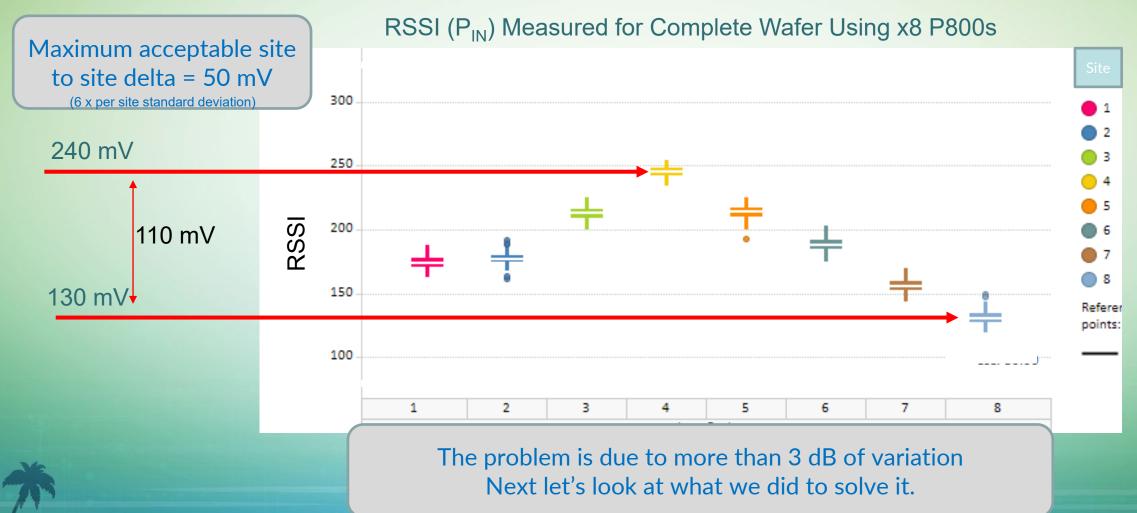
This presentation focuses on RSSI data collection



Problem Discussion

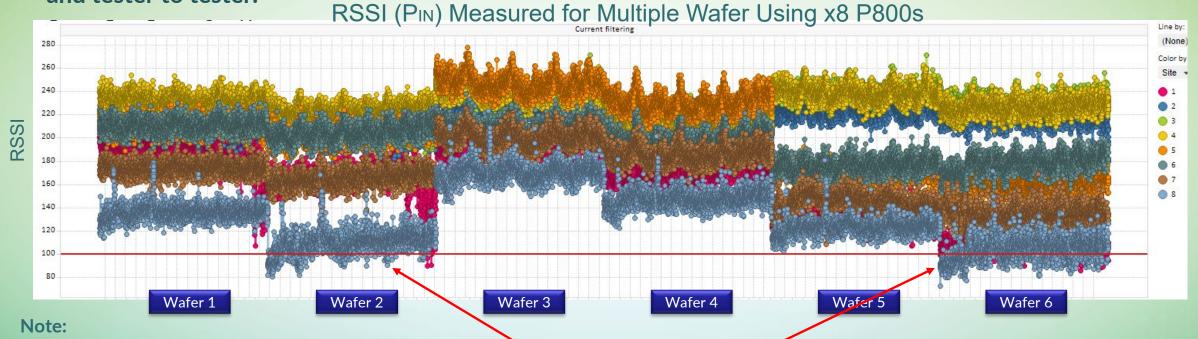
Observed:

There is more than 3 dB (110 mV) difference between site 1 and site 8.



Problem Discussion

• Observed variability in measurement data for site to site (8 sites), wafer to wafer, probe card to probe card and tester to tester.



- Each plot is 1 tested die on a wafer
- Data comes from different test setup conditions (different testers, different probe eards & cores)
- Data below red line resulted in a test failure.

!! Yield loss impact !! And CpK below 1



Model and Hypothesis (Analysis)

- Model 1: Core + PCB X
- Model 3: Semi Rigid Cable
- Model 2: Core to Board Interface
- Model 4: Bridge Beam + Shim + PC interaction





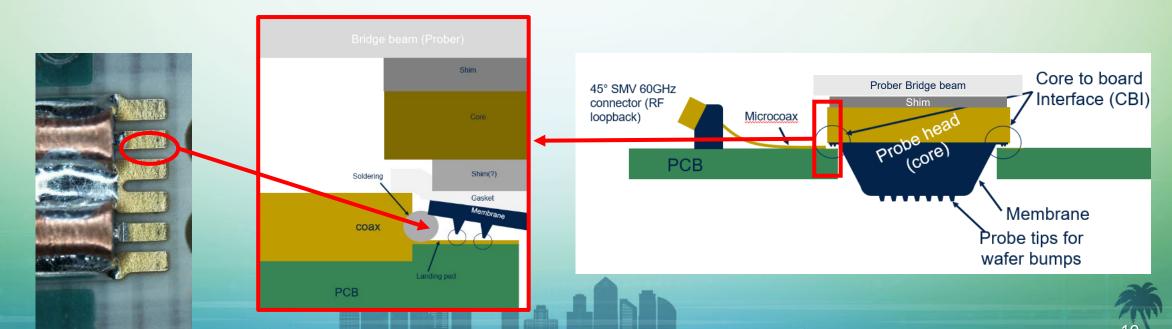
Core + PCB Testing

Observation: Not all bumps at the CBI make contact with the PCB pad.

Hypothesis: Interference between membrane & coax makes only 1 contact/imprint at CBI.

- Built a model to study bump & pad.
- Model shows no significant difference with 1 or both bumps touching down on PCB
- Kapton tape is 30 um thick and produced a 3 dB effect. (similar difference in RSSI)

Not the Problem



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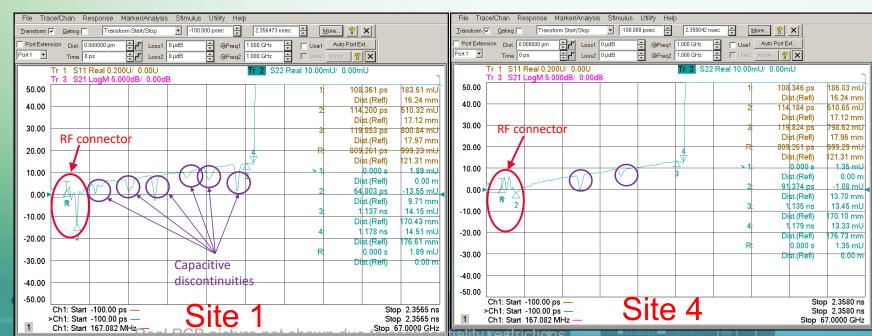
Semi Rigid Cable

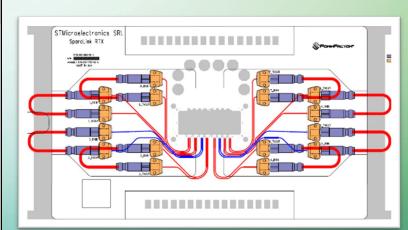
Observation: Semi rigid cable was length matched (600 ps +/- 2.5 ps) but some had more bends than others.

Hypothesis: Bends in cable causing discontinuities that are leading to attenuation issues.

- Minimum on sites 4 & 5 and most on 1 & 8. (also max number of cable bends)
- It's known that there is about 3 dB difference between site 1 and site 4.
- IL measurements of site 1 & 4 show < 0.2 dB difference.

Not the Problem





Bridge Beam vs Core Interference

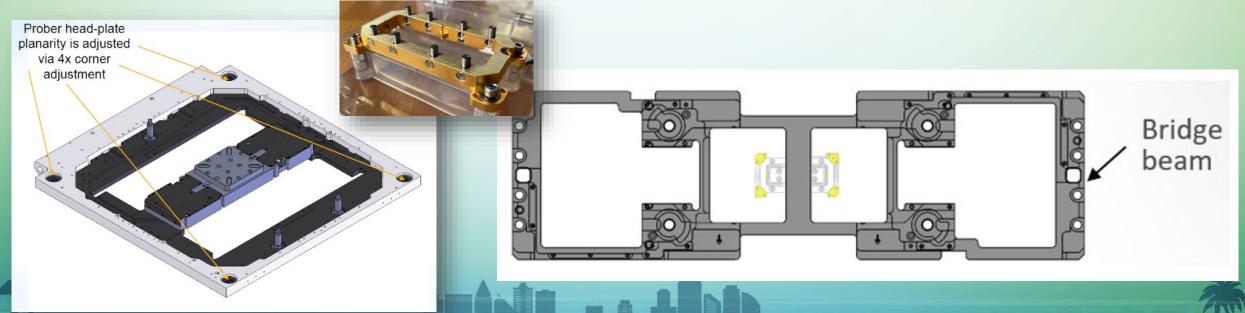
Observation: Different test cells were producing different results for the same Probe Card (PC)

Hypothesis: Lack of planarity and uniform pressure of the bridge beam and core was causing attenuation issues.

Special fixture was designed and manufactured to measure the interference

It was found that the planarity and interference was within spec for the test setup

Not the Problem



Bridge Beam Interaction

Observation: Numerous configurations have shown that mechanical forces negatively impact the RSSI.

Hypothesis: There is a PCB + Core interaction that affects the RSSI measurements

 Using combinations of shims, docking and undocking, tape and Over Drive (OD) it was possible to affect the RSSI level measured.

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This effect was not seen on any other application. Was unique to this design.

Bridge beam interaction effects were eliminated by moving all attenuators from the PCB to the membrane.

Force applied by prober docking stack

Docking interference exerts pressure on the core and PCB

Probe her

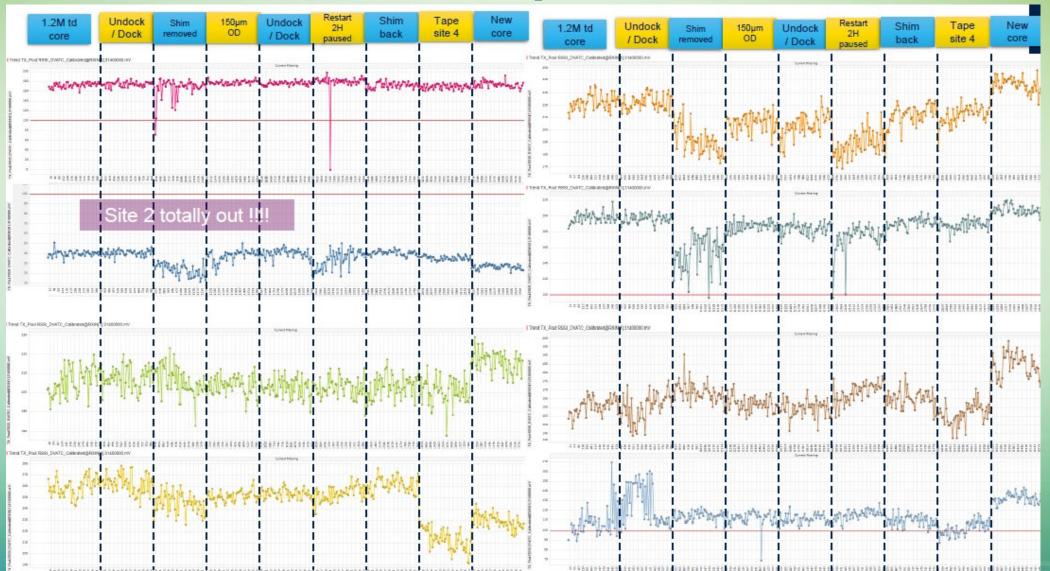
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Analysis

RSSI Manipulation





- Attenuator Trade Off Analysis
- Coupler Theory
- Design Considerations
- 50 Ω Trick
- Simulation
- Measurements (Validation)
- Results (Summary)

Using "on membrane attenuators" solves our problem. Let's look at how this is implemented...

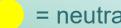




Attenuator Trade Off Analysis

Design Consideration	Resistive	Coupler	TX Line
60 GHz Operation			
RL Performance			
Crosstalk/Coupling	N/A	N/A	
Area (minimum)			
Design Complexity			
Routing Considerations			
Assembly Error			
SMT Quantity			
- had = neutral = good			







Next let's look at what a coupler attenuator is!

Note:

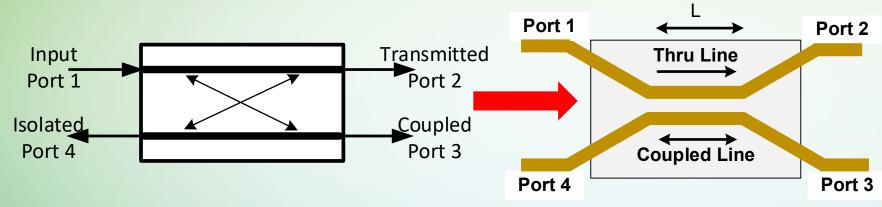
Ranked highest to lowest importance.

Resistive and TX line attenuator is least suitable. It will not be considered any further in this presentation...



Coupler Theory

Coupler Definition (Ideal): Directional device where power suppled to port 1 (input) is coupled to port 3 (coupled port) while the remaining power is delivered to port 2 (transmitted port). There is no power at port 4 (isolated port).



Impossible to build a perfect coupler, there will be unwanted coupling:

Directional holds: Sij=Sji

S21=S42=S12=S24 – TX paths are equal

S31=S42=S13=S24 - Coupled paths equal

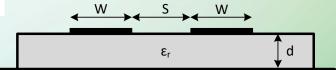
Not perfectly matched: S11=S22=S33=S44

Limited directionality: S41=S32
Reverse coupling exists: S13=S42

$S = \begin{bmatrix} S_{11} & S_{21} & S_{31} & S_{41} \\ S_{21} & S_{11} & S_{41} & S_{31} \\ S_{31} & S_{41} & S_{11} & S_{21} \end{bmatrix}$

Symmetric coupler:

- Symmetry in x and y.
- Requires that $\theta = \pi/2$ which means L= $\lambda/4$.
- λ =C/f at center frequency



S41≠0 is very important
This characteristic will be used in the design of the attenuator coupler.

Design Considerations

Design Requirements for Attenuator

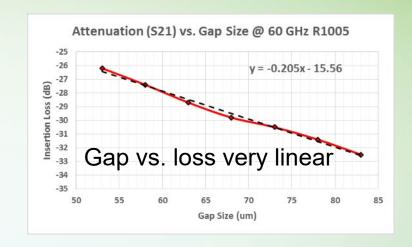
- Center Frequency (fc) = 60.5 GHz
- PTX MAX = 6 dBm ~ 4 mW -> 01005 resistors
- Attenuation = 26 dB
- Bandwidth (BW) = 500 MHz

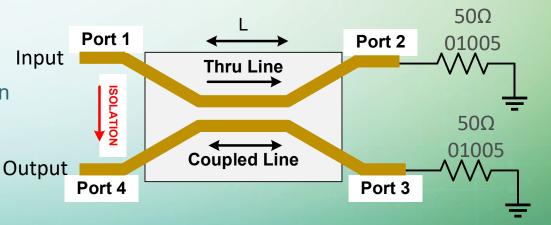
Uses 2-ASK modulation (1 bit/symbol)Data rates for USB 2.0 (480 Mbit/s)
BW = (480 Mbit/s)/(1 bit/symbol) = 480 MHz ~= 500 MHz

Note: ASK signal requires a bandwidth equal to its baud (symbol rate)

- FFI membrane design rules provide excellent line width control for microwave circuits.
- With FAB variations of +/- 2 um allows us to hold the center attenuation to +/- 0.4 dB
- Designed on 2 metal layer membrane
- Coupler attenuator technology available for new membrane design.



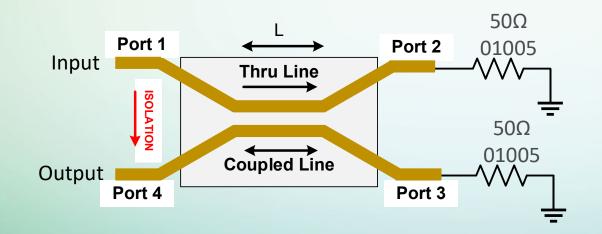


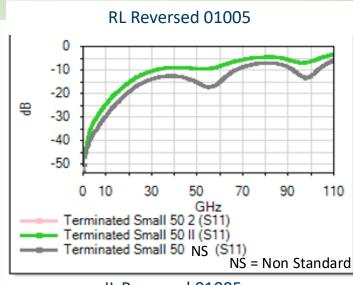


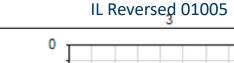


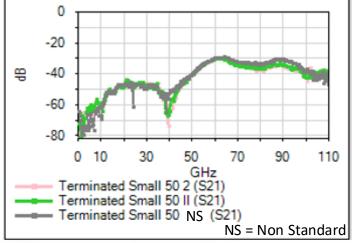
50 Ohm Trick

- Observed large improvement when the resistor is mounted in a non-standard configuration.
 - Normal: RL < -10 dB @ ~30 GHz
 - Non-standard: RL < -10 dB @ ~65 GHz
 - Best used with 60 GHz coupler









Simulation

Simulation:

- The coupler design was simulated in HFSS
- The red trace is a gap of 42 um and green trace is for 52 um.

Insertion Loss (IL):

- The simulated IL at 60 GHz is reasonable.
- Model predicted 52 um achieves the required 26 dB of attenuation.

Return Loss (RL):

RL=-25 dB at 60 GHz is acceptable.

HFSS Simulation A second seco

Simulated Coupler Insertion Loss (IL)



Simulated Coupler Return Loss (RL)

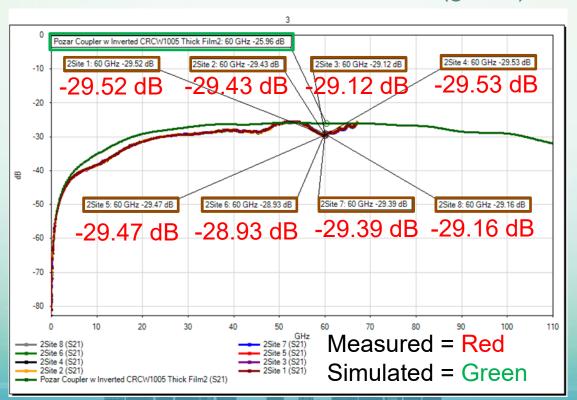


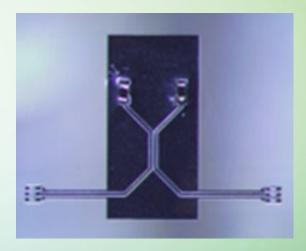
Measurements

(Validation)

- All 8 sites have an IL of approximately 29 dB. This is 3 dB below the simulated IL of 26 dB.
- Future work to perform additional work to identify why there is a 3 dB delta
- 3 dB more of IL is a benefit. It moves the receiver into a more linear region of operation.

IL For Sites 1-8 + HFSS Simulation (green)





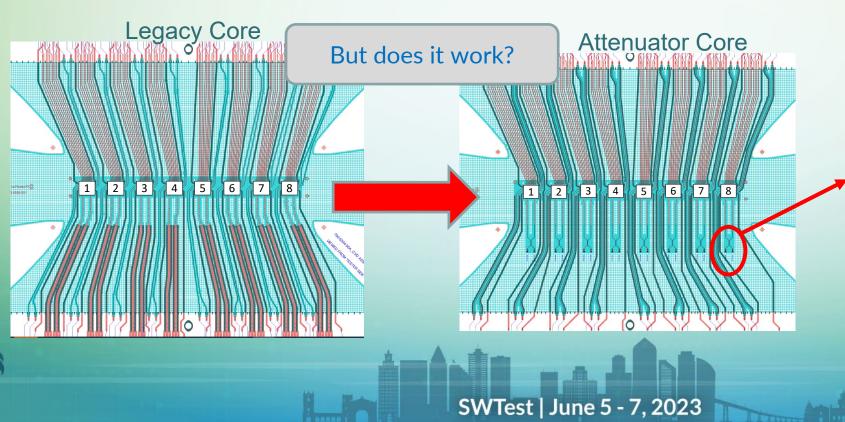
Data is fc = 60 GHz for 8 sites on a core.

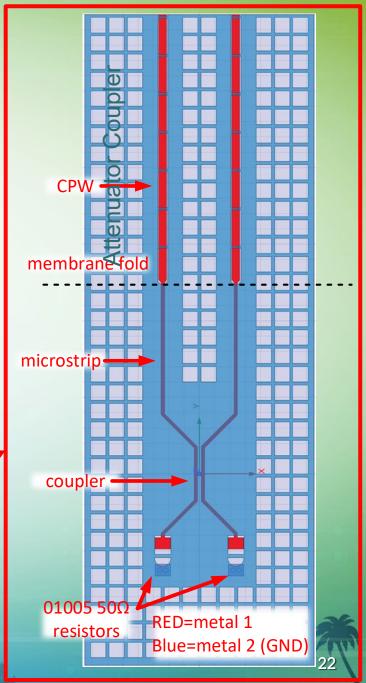




The final membrane (Attenuator Core):

- x8 design with no RF traces routed off the membrane
- 8 couplers (attenuator) designed into the south wing of the membrane
- final attenuator design results in 29 dB of attenuation





Validation

- Validation Process With RSSI (20k Die)
- Product Improvement

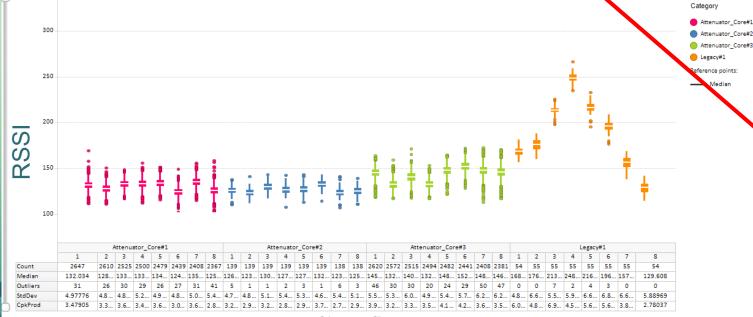
Validation

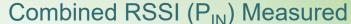
Validation Process With RSSI (20k Die)

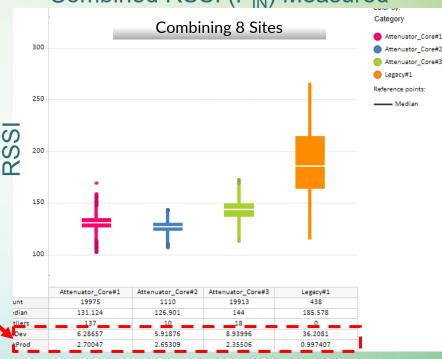
Comparing legacy and attenuator core:

- StdDev of legacy core is 5x that of attenuator core (36 mV to 6 ~ 9 mV)
- CpK of attenuator core is above 2 (now passing)
- Initially 20k die tested (small sample)
- These results are a MAJOR achievement

RSSI (P_{IN}) Measured for Complete Wafer Using x8 P800s



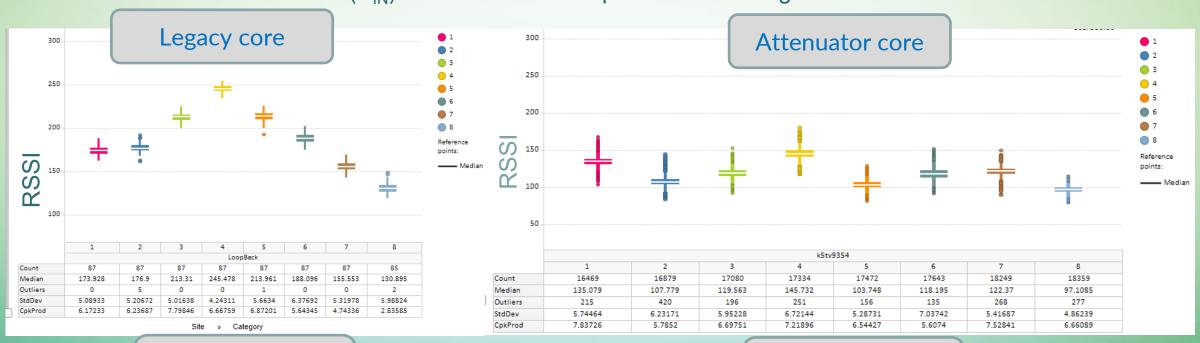




Production Improvement

- On production mode after ~200 k die tested, attenuation remains stable and site variation is ok
- No more event of yield loss





115 mV of delta for median values

50 mV of delta for median values

Conclusion

- By moving attenuators to the membrane, attenuation over 8 test sites showed an improved standard deviation of 0.35 dB on two membranes, where the previous membrane version showed 1.5 dB. This amounts to a 77% standard deviation reduction.
- Additionally with the attenuator core:
 - RSSI hump has been resolved.
 - In production STMicroelectronics observed very good predictability and stability of core performance
 - STMicroelectronics considers this a great achievement on their production test



Finish



